



PRODUCT DATA SHEET

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Datasheet



Resources

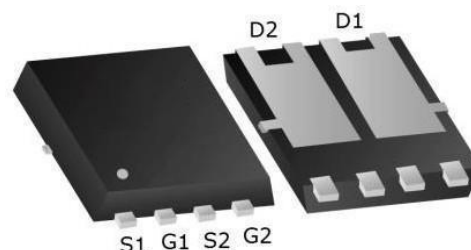


Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Product Summary

BVDSS	RDSON	ID
60V	10mΩ	30A

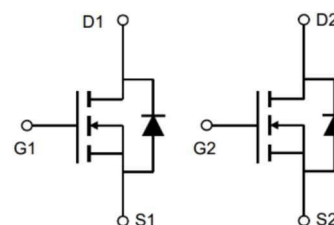

DFN3333-8L

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications



Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _C = 25°C	30	A
		T _C = 100°C	15	A
I _{DM}	Pulsed Drain Current ^{note1}		90	A
E _{AS}	Single Pulsed Avalanche Energy ^{note2}		36	mJ
P _D	Power Dissipation	T _C = 25°C	60	W
R _{θJC}	Thermal Resistance, Junction to Case		2.5	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =20A	-	10	13	mΩ
		V _{GS} =4.5V, I _D =10A	-	13	20	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	930	-	pF
C _{oss}	Output Capacitance		-	230	-	pF
C _{rss}	Reverse Transfer Capacitance		-	8	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =20A, V _{GS} =10V	-	22	-	nC
Q _{gs}	Gate-Source Charge		-	4.5	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	3.5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =30V, I _D =20A, R _G =1.6Ω, V _{GS} =10V	-	4.5	-	ns
t _r	Turn-on Rise Time		-	2.7	-	ns
t _{d(off)}	Turn-off Delay Time		-	13.8	-	ns
t _f	Turn-off Fall Time		-	2.7	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	23	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	90	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	T _J =25℃, I _F =20A,dI/dt=100A/μs	-	18	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	12	-	nC

Notes: 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition: $T_J=25^{\circ}\text{C}, V_{DD}=30V, V_G=10V, R_G=25\Omega, L=0.5mH, I_{AS}=12A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure1: Output Characteristics

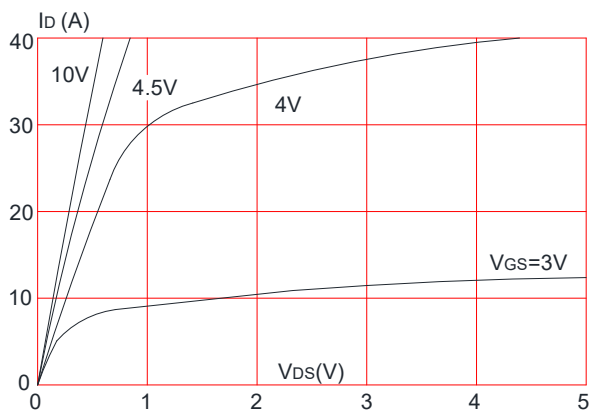


Figure 2: Typical Transfer Characteristics

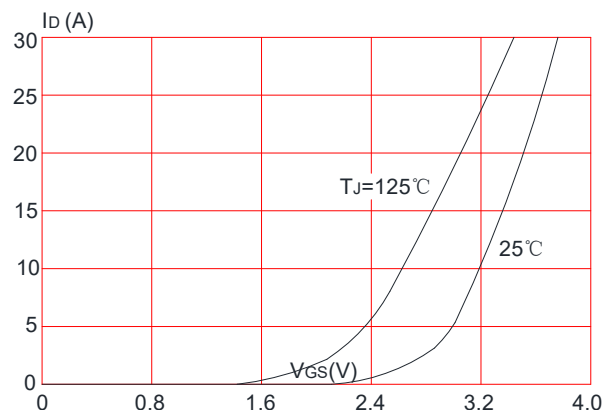


Figure 3: On-resistance vs. Drain Current

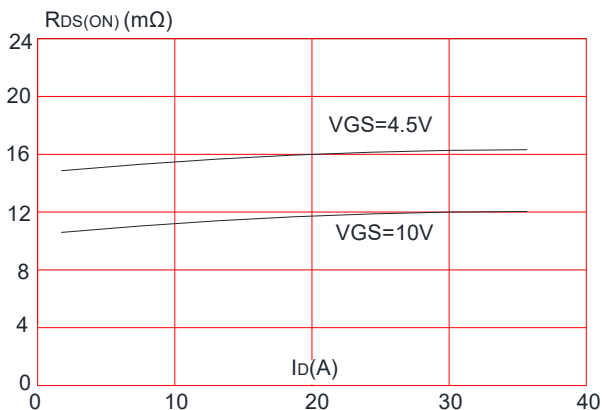


Figure 4: Body Diode Characteristics

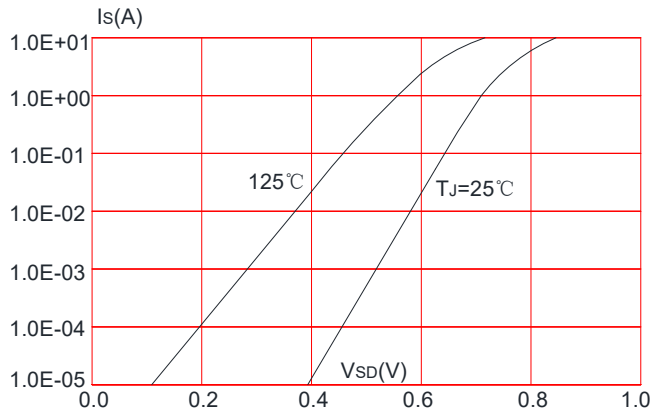


Figure 5: Gate Charge Characteristics

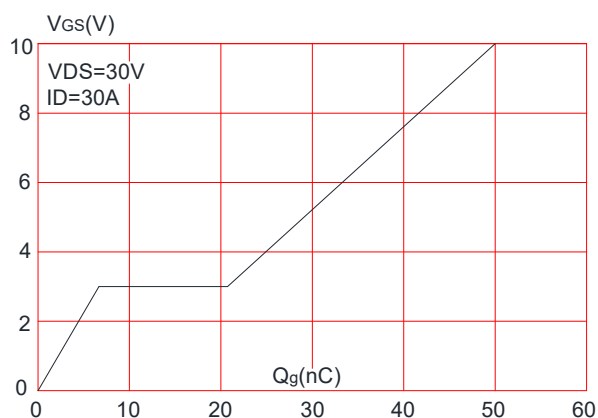


Figure 6: Capacitance Characteristics

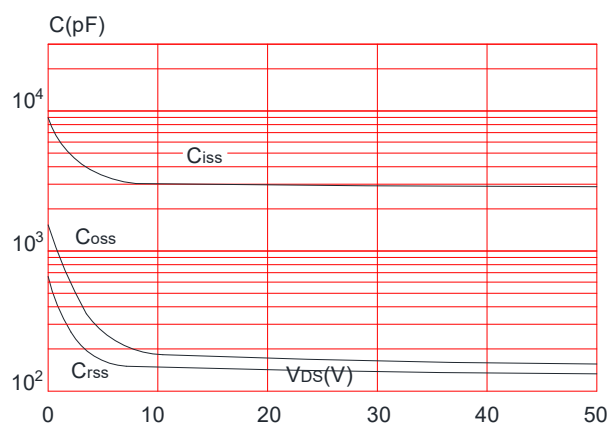


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

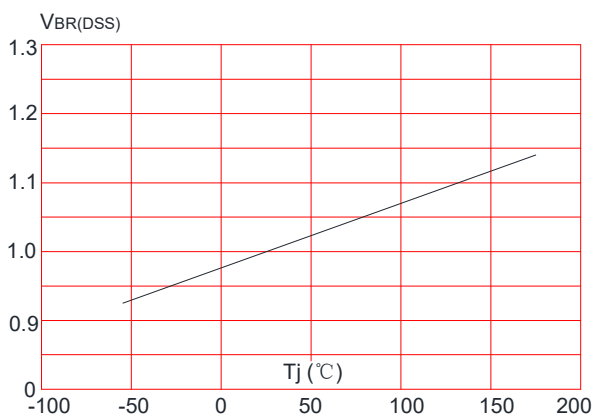


Figure 8: Normalized on Resistance vs. Junction Temperature

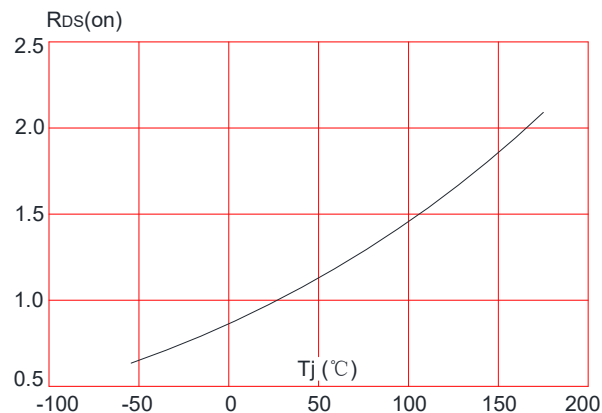


Figure 9: Maximum Safe Operating Area

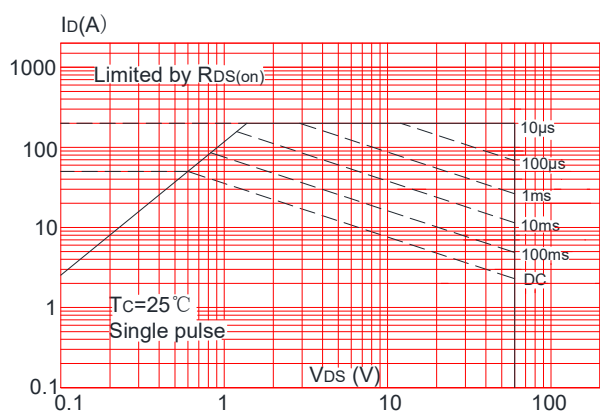


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

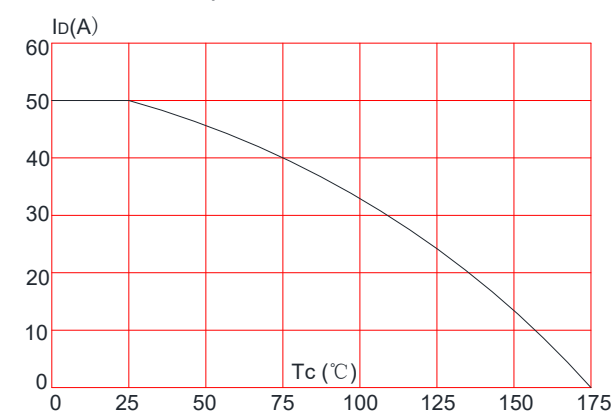
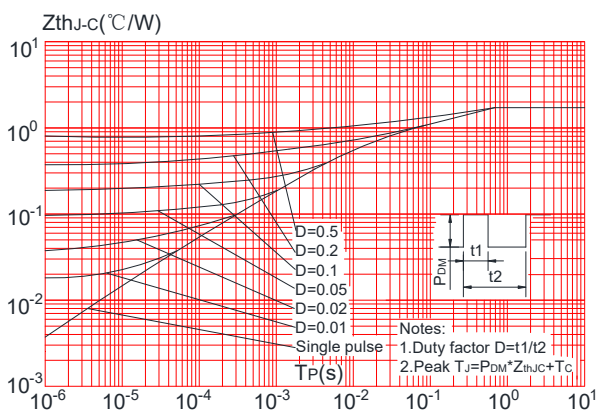
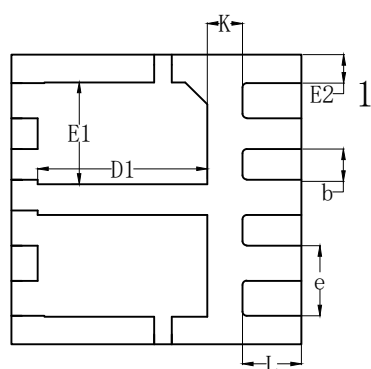
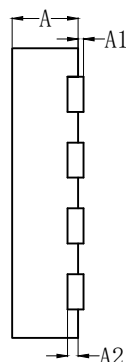
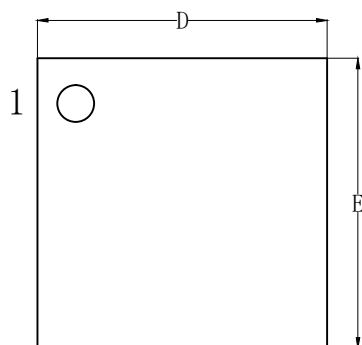


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case



Dual DFN3333-8L Package Outline Data


SYMBOL	MILLMETER		
	MIN	NOM	MAX
A	0.50	0.55	0.60
	0.70	0.75	0.80
	1.05	1.10	1.15
A1	0.00	—	0.05
A2	0.203 TIY		
b	0.30	—	0.40
D	3.25	3.30	3.35
D1	1.65	1.75	1.85
E	3.25	3.30	3.35
E1	1.06	1.16	1.26
E2	0.325 TIY		
e	0.75 BSC		
K	0.55 BSC		
L	0.57	0.67	0.77

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